

GSMDC3903Z

30V P-Channel MOSFETs

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

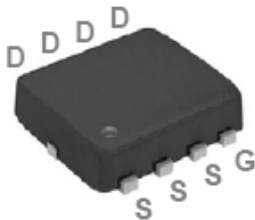
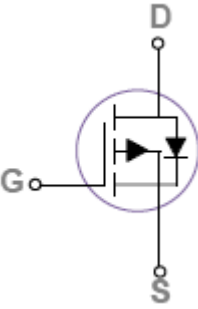
Features

- -30V, -50A, $R_{DS(ON)}=9.5m\Omega@V_{GS}=-10V$
- Fast switching
- Suit for -4.5V Gate Drive Applications
- ESD HBM Typ. 2KV Available
- Green Device Available
- DFN3X3-8L package design

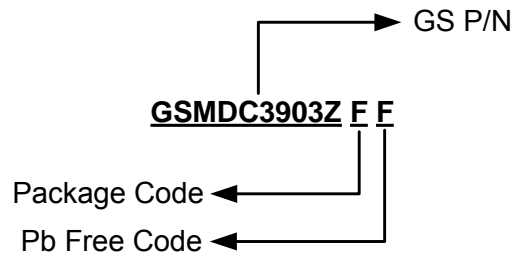
Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

Packages & Pin Assignments

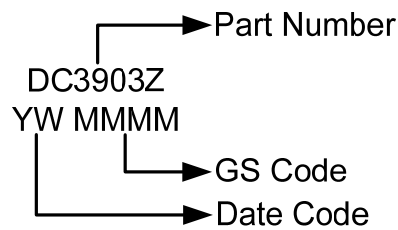
GSMDC3903ZFF (DFN3X3-8L)	
 <p>Top View</p>	
	
Pin	Description
1	Source
2	Source
3	Source
4	Gate
5	Drain
6	Drain
7	Drain
8	Drain

Ordering Information



Part Number	Package	Quantity Reel
GSMDC3903ZFF	DFN3X3-8L	3000 PCS

Marking Information



Absolute Maximum Ratings

T_C=25°C Unless otherwise noted

Symbol	Parameter	Typical	Unit
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current	T _C =25°C	-50
		T _C =100°C	-32
I _{DM}	Pulsed Drain Current	-200	A
P _D	Power Dissipation (T _C =25°C)	66	W
	Power Dissipation (Derate above 25°C)	0.53	W/°C
T _J	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient	62	°C/W
R _{θJC}	Thermal Resistance-Junction to Case	2	°C/W

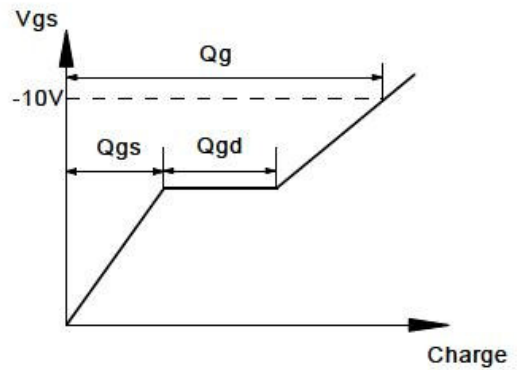
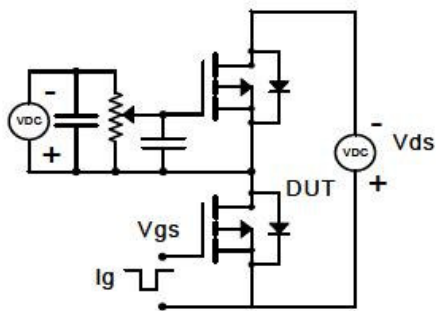
Electrical Characteristics

T_J=25°C Unless otherwise noted

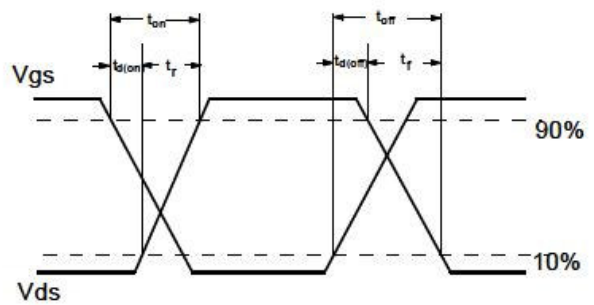
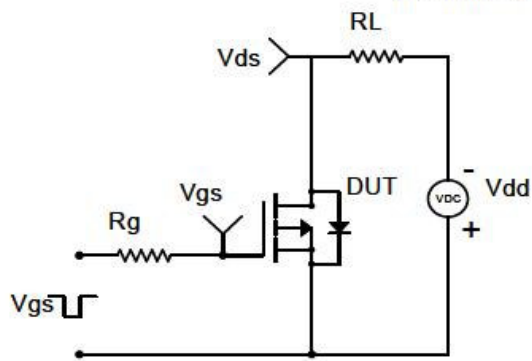
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30			V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA		-0.03		V/°C
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-1.2	-1.6	-2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient			4		mV/°C
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =125°C			-10	
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			-50	A
I _{SM}	Pulsed Source Current				-100	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-10V, I _D =-15A			9.5	mΩ
		V _{GS} =-4.5V, I _D =-10A			15	
g _{FS}	Forward Transconductance	V _{DS} =-10V, I _D =-10A		13		S
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A			-1	V
Dynamic						
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-10A		35	56	nC
Q _{gs}	Gate-Source Charge			10.8	16	
Q _{gd}	Gate-Drain Charge			10.6	16	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz		3300	5000	pF
C _{oss}	Output Capacitance					
C _{rss}	Reverse Transfer Capacitance					
t _{d(on)}	Turn-On Time	V _{DD} =-15V, I _D =-1A, V _{GS} =-10V, R _G =6Ω		24.5	38	ns
t _r				10.5	16	
t _{d(off)}	Turn-Off Time			156.8	230	
t _f				50	75	

Typical Performance Characteristics

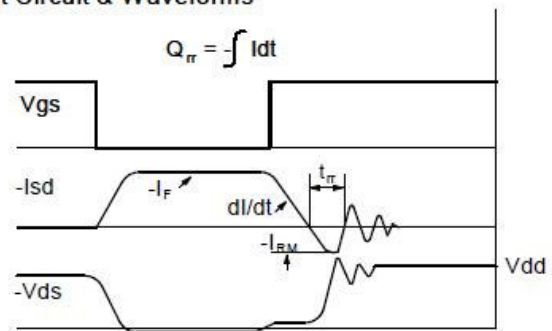
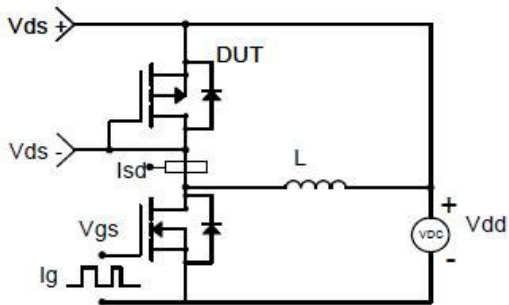
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

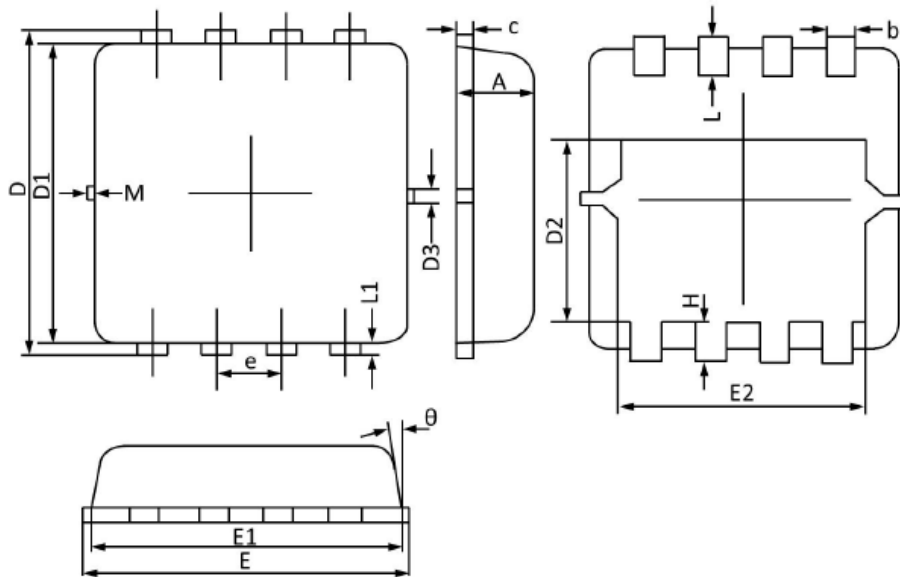


Diode Recovery Test Circuit & Waveforms



Package Dimension

DFN3X3-8L







Dimensions




Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 (REF)		0.005 (REF)	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 (BSC)		0.026 (BSC)	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 (REF)		0.005 (REF)	
θ	0°	12°	0°	12°
M	0.150 (REF)		0.006 (REF)	



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